

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L21	18	29/25.01.ccls. and ((die or chip or ic or circuit or device or pellet) near3 (attach\$4 or affix\$4 or mount\$4 or adher\$4 or bond\$4) and (wirebond\$4 or wire near bond\$4) and (singul\$5 or dicing or diced or scrib\$4 or cleav\$4 or sawing or cutting) and (mold\$4 or overmold\$4 or encapsul\$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 14:25
L19	16	700/121.ccls. and ((die or chip or ic or circuit or device or pellet) near3 (attach\$4 or affix\$4 or mount\$4 or adher\$4 or bond\$4) and (wirebond\$4 or wire near bond\$4) and (singul\$5 or dicing or diced or scrib\$4 or cleav\$4 or sawing or cutting) and (mold\$4 or overmold\$4 or encapsul\$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 14:24
L20	28	29/25.01.ccls. and (packag\$4 or housing) near6 (automat\$4 or robotic or computer\$5 or in-line or pipeline or pipe-line or unmanned)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 14:22
L18	33	700/121.ccls. and (packag\$4 or housing) near6 (automat\$4 or robotic or computer\$5 or in-line or pipeline or pipe-line or unmanned)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 14:22
L17	586	438/107,113,458,460.ccls. and ((die or chip or ic or circuit or device or pellet) near3 (attach\$4 or affix\$4 or mount\$4 or adher\$4 or bond\$4) and (wirebond\$4 or wire near bond\$4) and (singul\$5 or dicing or diced or scrib\$4 or cleav\$4 or sawing or cutting) and (mold\$4 or overmold\$4 or encapsul\$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 14:20
L16	163	438/107,113,458,460.ccls. and (packag\$4 or housing) near6 (automat\$4 or robotic or computer\$5 or in-line or pipeline or pipe-line or unmanned)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 14:14
L14	30	257/E23.18.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 13:58

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L13	68	257/E25.022.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 13:58
L12	392	257/798.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 13:54
L7	578	438/112.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 13:46
L6	430	438/111.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 13:25
L2	464	438/110.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 13:02
S98	12	(asic or (diversified or small near quantity) near4 (ic or chip or die or circuits or devices)) near5 (packag\$4 or hous\$4) near6 (automat\$6 or robotic\$4 or computer\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 13:01
L4	0	(asic or (diversified or small near quantity) near4 (ic or chip or die or circuits or devices)) near5 (packag\$4 or hous\$4) near6 (unmanned or unmanning)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 13:01
L3	2	"6173750".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 12:54
S10 3	16	(ic or chip or die) same (backend or back-end or back-of-line or front-of-line) same (pipeline or pipe-line or in-line or robotic\$5 or automat\$5) and (wirebond\$4 or wire near bond\$4) and (chip or die or ic or pellet) near4 (mount\$4 or attach\$4 or affix\$4 or adher\$5 or secur\$4) and (dicing or diced or cutting or sawing or singulat\$4 or cleav\$4 or scrib\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 12:38

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S10 2	1	((small near scale) near10 (ic or chip or die or circuits or devices)) near10 (backend or back-end or back-of-line or front-of-line) same (pipeline or pipe-line or in-line or robotic\$5 or automat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 11:14
S10 1	7	(asic or (diversified or small near quantity) near10 (ic or chip or die or circuits or devices)) near10 (backend or back-end or back-of-line or front-of-line) same (pipeline or pipe-line or in-line or robotic\$5 or automat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 11:13
S10 0	29	(asic or (diversified or small near quantity) near10 (ic or chip or die or circuits or devices)) near10 (packag\$4 or hous\$4) same (pipeline or pipe-line or in-line)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 11:12
S97	112	(asic or (diversified or small near quantity) near4 (ic or chip or die or circuits or devices)) near5 (packag\$4 or hous\$4) and (wirebond\$4 or wire near bond\$4) and (mold\$4 or encapsul\$5) and (chip or die or ic or circuit or device or pellet) near4 (mount\$4 or attach\$4 or affix\$4 or secur\$4 or adhesive or adher\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 11:08
S96	143	(automated or automatic or robotic or computer\$5) near2 (chip or die or ic or bga) near5 (packag\$4 or assembl\$4 or housing) and (in-line or pipeline or pipe-line or conveyor or continuous) and (mold\$3 or encapsul\$4 or wirebond\$4 or wire near bond\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 10:59
S91	298	(automated or automatic or robotic or computer\$5) near2 (chip or die or ic or bga) near5 (packag\$4 or assembl\$4 or housing) and (in-line or pipeline or pipe-line or conveyor or continuous)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 10:29
S95	226	(ic or integrated adj circuit or die or chip) near5 (back near end or end near line or back near line) and (bonding or bonded or attachment or flip adj chip or attaching or adhering) and (plasma or cure or curing or anneal or annealing or cured or annealed)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 10:28
S94	4	("5173766" "5541524" "5851664" "6566745").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/28 10:14

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S93	1	("6173750").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/28 10:13
S92	13	("4928002" "5943551" "6096093" "6129278" "6154714" "6337221" "6367042" "6392427" "6730532" "6730545" "6875640" "6901984" "6931298").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/28 10:08
S89	1086	(automated or automatic or robotic or computer\$5) near2 (chip or die or ic or bga) near5 (packag\$4 or assembl\$4 or housing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 09:46
S86	344	(automated or automatic or robotic or computer\$5) near2 (chip or die or ic or package) near3 (testing or test or tested or inspection or inspecting or inspected or sorting or sorted) and (chip or die or ic or package) near3 (assembly or assembling or packaging or packaged or attach or attaching or attachment or mounting or mounted)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 09:44
S85	131	(automated or automatic or robotic or computer\$5) near2 (chip or die or ic or package) near3 (dicing or diced or singulating or singulation or singulated or cleaving or cleaved or cleaver or scribing or cutting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 09:07
S84	274	(automated or automatic or robotic) near2 (chip or die or ic) near3 (conveyor or conveying or conveyance or movement or mover or moving or transfer or transferring or transferral or handling or handler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 08:40
S83	332	(die or chip or ic) near3 (strip or array or panel or tape or reel) near15 (assembly or assembling or packaging or packaged or assembled) near15 (automated or automatic or robotic or computerized or in-line or inline)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 17:09
S82	123	(back-of-line or end-of-line or back-end) near2 (assembly or assembling or processing or packaging) and (die or chip or wafer or device or ic) near2 (tape or strip or array)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 16:55
S81	29	("4301958").URPN.	USPAT	OR	ON	2006/04/27 16:46
S80	10	("5549716").URPN.	USPAT	OR	ON	2006/04/27 16:40

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S79	228	(automatic or automated or automating or robotic) near4 (packaging or package or assembly) same (die or chip or ic) near3 (attaching or attach or attached or bonding or bonded or bond) same (wirebonding or wirebond or wire near bonding or wire near bonded or wirebonded or wire near bond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 16:38
S78	78	(ic or integrated adj circuit or die or chip) near2 (line) near2 (packaging or package or assembly or assembling or manufacturing or manufacture) same (dicing or diced or singulation or singulated or singulating or cleaved or cleavage or cleaving or scribing or scribed or scribe or cutting or separating or separation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 16:30
S77	32	"5549716".pn. "6465743".pn. "4674670".pn. "5336931".pn. "5499717".pn. "20020177875" "6522940".pn. "3814895".pn. "6574858".pn. "6049624".pn. "5915231".pn. "4301958".pn. "5865319".pn. "6230719".pn. "6105783".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 16:21
S76	127	(ic or integrated adj circuit or die or chip) near2 (packaging or package or assembly or back adj end or line or "in-line" or back near line) near2 (system or apparatus or machine) and (attachment or attaching or flip adj chip or bonding or bonded or adhering) same (cure or curing or thermal or plasma or anneal or annealing or cured or annealed) and (singulating or singulation or singulated or cutting or cut or sawing or sawed or dicing or diced or cleaving or cleavage or cleaved) same (test or testing or tested or sorting or sorted or sorter or sort)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 16:20
S75	226	(ic or integrated adj circuit or die or chip) near5 (back near end or end near line or back near line) and (bonding or bonded or attachment or flip adj chip or attaching or adhering) and (plasma or cure or curing or anneal or annealing or cured or annealed)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 15:59

Interference Search

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L22	26	((chip or die or ic or circuit or device) near6 (packag\$4 or housing or assembl\$4) and (front-of-line or end-of-line or back-end)).clm.	US-PGPUB	OR	ON	2006/04/28 14:36
L24	70	((chip or die or ic or circuit or device) near6 (packag\$4 or housing or assembl\$4) near5 (in-line or inline or pipeline or pipe-line)).clm.	US-PGPUB	OR	ON	2006/04/28 14:32
L25	11	((chip or die or ic or circuit or device) near6 (packag\$4 or housing or assembl\$4) near5 (in-line or inline or pipeline or pipe-line) and (encapsulat\$4 or mold\$4 or overmold\$4 or wirebond\$4 or wire near bond\$4)).clm.	US-PGPUB	OR	ON	2006/04/28 14:33
L26	0	((chip or die or ic or circuit or device) near6 (packag\$4 or housing or assembl\$4) near5 (in-line or inline or pipeline or pipe-line) and (size or length or width) near2 (independen\$4 or insensitiv\$4 or computer or database)).clm.	US-PGPUB	OR	ON	2006/04/28 14:34
L27	52	((chip or die or ic or circuit or device) and (mold\$4 or encapsulat\$4 or overmold\$4) and (ball or solder) near2 (attach\$4 or affix\$4 or adhering or placement or placing) and (chip or die or ic or circuit) near3 (mount\$4 or attach\$4 or assembl\$5 or affix\$4 or adher\$5) and (sawing or cutting or singulat\$4 or scribe\$4 or cleav\$4 or dicing or diced)).clm.	US-PGPUB	OR	ON	2006/04/28 14:36
L29	42	((chip or die or ic or circuit or device) near6 (packag\$4 or housing or assembl\$4) near5 (automat\$4 or robot\$4 or unmanned or computerized) and (mold\$4 or overmold\$4 or encapsulat\$4 or wirebond\$4 or wire near bond\$4)).clm.	US-PGPUB	OR	ON	2006/04/28 14:37